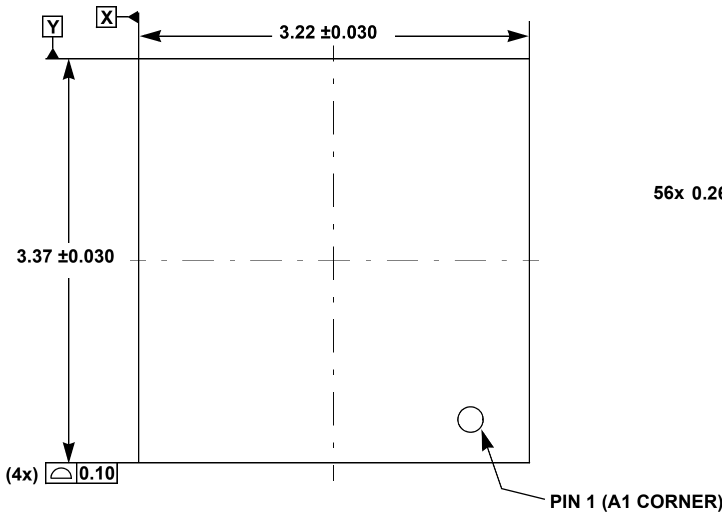
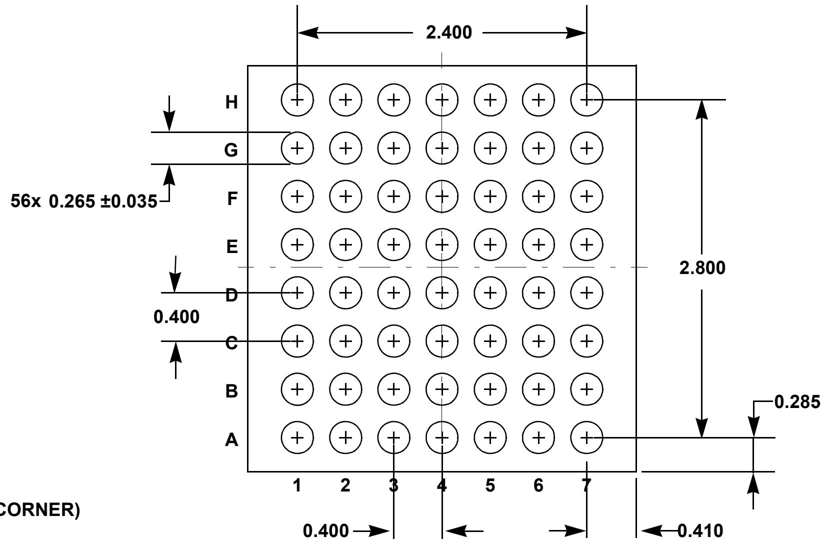
Package Outline Drawing

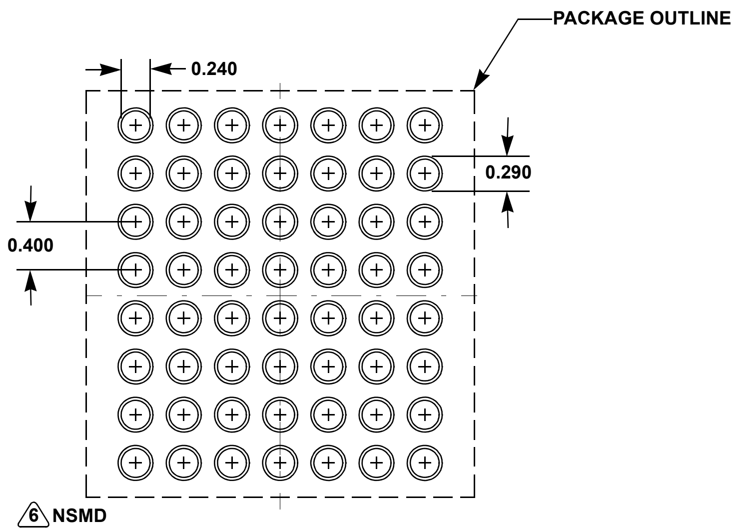
W7x8.56A

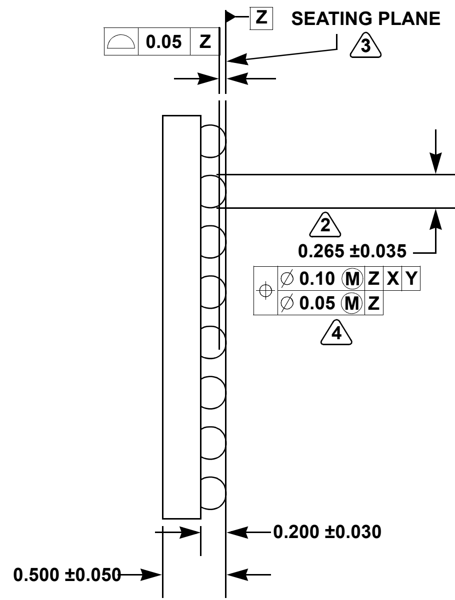
56 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

Rev 0, 6/14









NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.
2. (△) Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. (△) Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. (△) Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
6. (△) NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.